CLAIMS

WE CLAIM:

1. An integrated circuit (IC) card for use in a data processing device, comprising:

an IC package having multiple leads extending from said package;

a casing that encases said package, such that when said casing is inserted into said data processing device, said leads provide an electrical interface between said IC package and said data processing device without the use of a printed circuit board and a connector.

2. The IC card of claim 1 wherein said casing has a front surface having a front opening, such that when said IC package is inserted into said casing, said IC package and said data processing device form said electrical interface through said front opening.

3. The IC card of claim 2 wherein said casing has a back surface having a back opening such that said IC package is inserted into said casing through said back opening.

4. The IC card of claim 3 wherein said casing has at least one stop at said back opening such that when said IC package is fully inserted into said casing, said stop holds said package securely within said casing.

5. The IC card of claim 2 wherein said casing has a bottom surface having a bottom opening such that said IC package is inserted into said casing through said bottom opening.

6. The IC card of claim 5 wherein said casing has at least one stop at said bottom opening such that when said IC package is fully inserted into said casing, said stop holds said package securely within said casing.

7. A method of assembling an integrated circuit (IC) card for use in a data processing device, comprising the steps of:

providing an IC package, said package having multiple leads extending from said package;

providing a casing; and,

inserting said package into said casing, such that when said casing is inserted into said data processing device said leads provide an electrical interface between said IC package and said data processing device without the use of a printed circuit board and a connector.

8. The method of claim 7 wherein said step of providing a casing includes providing a casing having a front surface with a front opening, such that when said IC package is inserted into said casing, said IC package and said data processing device form said electrical interface through said front opening.

9. The method of claim 8 wherein said step of providing a casing includes providing a casing having a back surface with a back opening, and said step of inserting said IC package includes inserting said IC package through said back opening of said casing.

10. The method of claim 9 where said step of providing a casing includes providing a casing having at least one stop on said back opening such that when said IC package is fully inserted into said casing through said back opening, said stop holds said IC package securely within said casing

11. The method of claim 8 wherein said step of providing a casing includes providing a casing having a bottom surface with a bottom opening, and said step of inserting said IC package includes inserting said IC package through said bottom opening of said casing.

12. The method of claim 11 wherein said step of providing a casing includes providing a casing having at least one stop at said bottom opening such that when said IC package is fully inserted into said casing through said bottom opening, said stop holds said IC package securely within said casing.

13. A method of connecting an integrated circuit (IC) to a receptacle of a data processing device, comprising the step of:

providing an IC package having multiple leads extending from said package; and,

inserting said IC package into said data processing device such that said leads from said IC package provide the electrical interface between said IC package and said data processing device without the use of a printed circuit board or a connector.

14. The method of claim 13 wherein said step of providing an IC package includes providing an IC package having a blade on pad socket device.